

TECHNICAL CHARACTERISTICS

Wafer Style 8WF Tweezers

- Composition**

Component	Wt.%	Component	Wt.%	Component	Wt.%
C	≤0.03	Si	≤1.0	Mn	≤2.0
P	≤0.045	S	≤0.03	Cr	17.0-19.0
Mo	2.5-3.0	Ni	12.5-15.0		

- Mechanical properties:**

State	annealed
Density	8.0 g/cm ³
hardness HB30	≤215
Hardness Rockwell B	79
Tensile strength, ultimate	500-700 MPa
Tensile strength, yield	290
0.2% Yield stress	≤200 MPa
Elongation, break	40%
Modulus of elasticity	200 GPa

- Thermal properties**

Coef. of lin. therm expansion	16.0 E-6/°C	20°C-100°C
Coef. of lin. therm expansion	17.0 E-6/°C	20°C-300°C
Specific heat capacity:	0.50 J/(g·K)	
Thermal conductivity:	15W/(m·K)	
Continuos use temperature:	350°C	
Max service temperature, ait	925°C	

- Electrical properties**

Resistivity	0.75 E-4 Ohm.cm
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